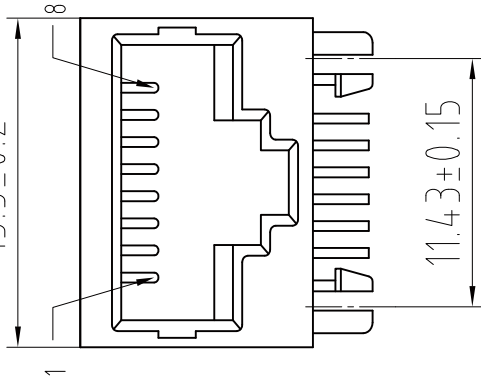
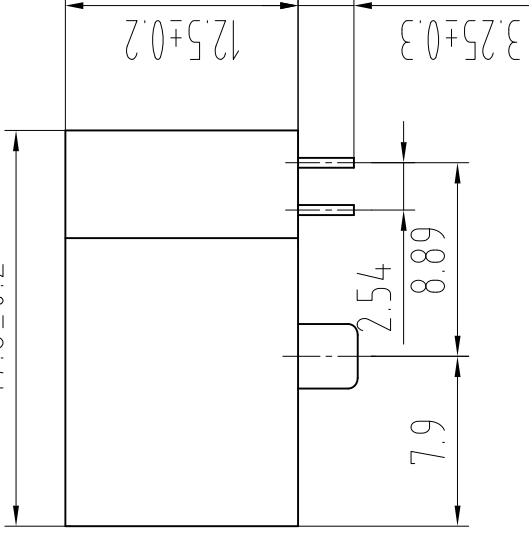


MAK.	Q.U.A.	Description	REV.	DRW.
A				
B				

15.3±0.2



17.6±0.2



NOTES:

MATERIAL :

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE ϕ 0.46mm.
- 3.PLATING :GOLD PLATING OVER NICKEL.

ELECTRICAL:

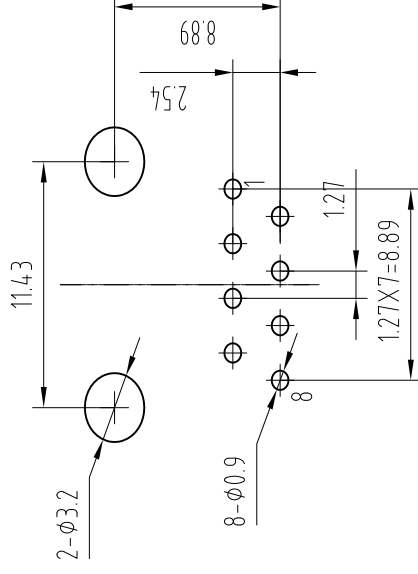
- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C~+85°C
2. OPERATION : -40°C TO 70°C.



PC Board Layout

Component Side Shown

Gen.Tolerance	Scale	Not
.X ± 0.20	Unit	mm
.XX ± 0.08	Size	ϕ
.XXX ± 0.05		
$\angle \pm 1^\circ$		

Scale	Not
Unit	mm
Size	ϕ

P/N # 5621-10P8C

RJ45 R/A 90

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Rev. A

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DRW by

APP by

AMY July 07 2011

Long July 11 2011

Chin July 11 2011